



Technology Service Corporation
an employee-owned company

Mechanical Engineer

Company Overview: Headquartered in Arlington, Virginia, TSC is an employee-owned company that has been providing high-quality technical services and solutions for our customers' for over 50 years. Our diverse portfolio includes providing full lifecycle support in Precision Strike And Area Effects; Area Protection; Airborne Sensors and Intelligence, Surveillance, and Reconnaissance (ISR); Vehicle Protection; Electronic Warfare Systems; Air And Missile Defense; Space Systems, and Intelligence and Information Systems. TSC offers a professional working environment, a competitive salary, and an excellent benefits package. Come and join our team!

TSC Operation Highlights

TSC's Systems Development and Production Division provides products and services in the areas of radar, communication systems, sensors, antennas and other electronics systems to the missile, radar/sensor system, communications, control systems, data acquisition, and signal processing markets. The company has developed products ranging from chip-level, application-specific, integrated circuits (ASIC) to complete, turnkey radar and communication systems. TSC has established a state-of-the-art hardware capability that is well respected by customers in Government and industry. TSC also provides full spectrum systems engineering support including theoretical analysis, requirements generation, interface control, and test planning/execution/data analysis.

Job Description:

The Physical Design Services Group at TSC's Systems Development and Production Division in Huntsville, AL is currently looking to hire a Mechanical Engineer with an education and industry focus in the mechanical/thermal design and packaging of electronics systems such as high density airborne or ruggedized electronics assemblies in support of radars/sensors, missile seekers and communications systems.

Responsibilities:

- Design, develop, modify and evaluate electronic packaging and antennae array systems for use in Mil/Aero applications.
- Model components and systems as well as create drawing packages for fabrication
- Perform structural and CFD thermal analyses of electronic systems
- Apply Design for Manufacturability (DFM) and Design for Assembly (DFA) techniques on both new and existing products to produce optimal design and manufacturing solutions.
- Support vibration and thermal testing of aerospace systems
- Perform quality inspections of incoming fabricated parts
- Support board and system builds
- Maintain responsibility of product from concept to production
- Interface with customers and vendors to ensure product/component performance to customer specifications and to appropriate standards.
- Activity management with intercompany resources and outside vendors in support of prototype fabrication, assembly and validation testing.

Qualifications

Required Qualifications:

- B.S in Mechanical Engineering from an accredited University
- 2-5 years of commensurate industry experience in analysis, design, and layout of electronics hardware components and/or systems

- Experience with military electronics packaging including RF, microwave, analog or digital assemblies and subassemblies
- Capable of weighing product design for manufacturability and cost attributes against product form-fit-function and thermal attributes to achieve the best mix for each unique product and customer requirement.
- Proficiency with SolidWorks, Solid Edge, Pro-E, or other 3D modeling software with SolidWorks
- Experience conducting CFD, Vibration, Shock, Static, and Thermal FEA
- Basic understanding of machining and electronic system manufacturing processes
- Experience with design for manufacturability and assembly
- Knowledge of MIL-STD-810G
- Understanding and Application of Geometric Dimensioning and Tolerancing (GD&T)
- Ability to read and generate mechanical drawings.
- Experience in 2D and 3D modeling.
- Experience working in a design team environment with vendors, customers and peer engineers
- DOD Program Experience

Preferred Qualifications:

- Experienced in the following software packages: Solidworks, Solidworks Simulation Premium, Autodesk Simulation CFD.
- Working knowledge of CFD thermal analysis software packages and FEA structural analysis software
- Experience in microelectronics packing.
- Experience designing welded structures
- Knowledge of PLM, PDM, and configuration control process
- Basic understanding of RF, microwave, analog and digital electronics packaging principles.
- Knowledge of military finishes.
- Experience in a multi-tasking environment and managing daily schedules and tasks to ensure overall program schedule and objectives are met.
- Familiar with Dynamic and Thermal Testing

U.S. Citizenship Required: Yes

Security Clearance Required: Yes, will be required to obtain and maintain a security clearance

Travel: Yes (0-25%)

Relocation Assistance Available: Yes

Position Contingent Upon Award of Contract: No

TSC Benefits:

TSC offers a stable work environment, a competitive salary and a comprehensive benefits package; including ESOP contributions, 401k Matching Program, Flexible Work Schedules, Tuition Reimbursement, Paid Leave and much more.

Applying to TSC:

Only those candidates invited for an interview will be contacted. Employment at TSC is contingent upon the successful completion of a comprehensive background check, security investigation, and a drug screening.

Send resumes to: Employment-HSV@tsc.com

TSC is committed to hiring and retaining a diverse workforce. We are proud to be an Equal Opportunity Employer/Affirmative Action Employer, making decisions without regard to race, color, religion, creed, sex, sexual orientation, gender identity, marital status, national origin, age, veteran status, disability or any other protected class.